

## Electronic Patent Application Fee Transmittal

Application Number:	10773517
Filing Date:	06-Feb-2004
Title of Invention:	METHOD AND APPARATUS FOR RAPID COOLDOWN OF ANNEALED WAFER
First Named Inventor/Applicant Name:	Chia-Chu Kuo
Filer:	Richard T. Ogawa/Joy Salvador
Attorney Docket Number:	021653-002700US

Filed as Large Entity

### Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Publ. Fee- early, voluntary, or normal	1504	1	300	300
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Petition:

Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Utility Appl Issue fee	1501	1	1400	1400
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	10	3	30
<b>Total in USD (\$)</b>				<b>1730</b>